Background Statement for SEMI Draft Document 5954

REAPPROVAL OF SEMI E15.1-0305 (REAPPROVED 1110) SPECIFICATION FOR 300 MM TOOL LOAD PORT

Notice: This background statement is not part of the balloted item. It is provided solely to assist the recipient in reaching an informed decision based on the rationale of the activity that preceded the creation of this Document.

Notice: Recipients of this Document are invited to submit, with their comments, notification of any relevant patented technology or copyrighted items of which they are aware and to provide supporting documentation. In this context, "patented technology" is defined as technology for which a patent has issued or has been applied for. In the latter case, only publicly available information on the contents of the patent application is to be provided.

Background
Per SEMI *Regulations* 8.9.1, the Originating TC Chapter shall review its Standards and decide whether to ballot the Standards for reapproval, revision, replacement, or withdrawal by the end of the fifth year after their latest publication or reapproval dates.

The NA PIC TC Chapter reviewed and recommended to issue for reapproval ballot.

Per SEMI *Procedure Manual* (NOTE 19), a reapproval Letter Ballot should include the Purpose, Scope, Limitations, and Terminology sections, along with the full text of any paragraph in which editorial updates are being made.

Voter requests for access to the full Standard or Safety Guideline must be made at least three business days before the voting deadline. Late requests may not be honored.

Review and Adjudication Information

	Task Force Review	**Committee Adjudication**
Group:	Global PIC Maintenance TF	PIC NA TC Chapter
Date:	April 5, 2016	April 6, 2016
Time & Timezone:	2:00-3:00 PM PDT	9:00 AM -12:00 PM PDT
Location:	Intel	Intel
City, State/Country:	Santa Clara, CA/USA	Santa Clara, CA/USA
Leader(s)/Authors:	Larry Hartsought (U A Associates)	Matt Fuller (Entegris) Stefan Radloff (Intel)
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This meeting's details are subject to change, and additional review sessions may be scheduled if necessary. Contact the task force leaders or Standards staff for confirmation.

Telephone and web information will be distributed to interested parties as the meeting date approaches. If you will not be able to attend these meetings in person but would like to participate by telephone/web, please contact Standards staff.

Check www.semi.org/standards on calendar of event for the latest meeting schedule.

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LETTER BALLOT

SEMI Draft Document 5954

REAPPROVAL OF SEMI E15.1-0305 (REAPPROVED 1110) SPECIFICATION FOR 300 MM TOOL LOAD PORT

1 Purpose

1.1 This specification defines dimensional requirements for the load ports of 300 mm wafer process and inspection equipment. It is intended to promote a uniform physical interface between equipment and the factory, to facilitate the use of automated wafer carrier transport systems, and/or to meet ergonomic requirements for manually loaded equipment.

2 Scope

2.1 This standard covers 300 mm equipment only. Similar requirements covering equipment for 200 mm wafers and smaller are covered in SEMI E15.

NOTICE: This standard does not purport to address safety issues, if any, associated with its use. It is the responsibility of the users of this standard to establish appropriate safety and health practices and determine the applicability of regulatory or other limitations prior to use.

3 Limitations

3.1 This standard is not met by direct loading/unloading of vacuum load locks. Requirements of such interfaces may differ from those in this document.

4 Referenced Standards and Documents

4.1 *SEMI Standards*

SEMI E1.9 — Mechanical Specification for Cassettes Used to Transport and Store 300 mm Wafers

SEMI E15 — Specification for Tool Load Port

SEMI E47.1 — Mechanical Specification for FOUPS Used to Transport and Store 300 mm Wafers

SEMI E57 — Mechanical Specification for Kinematic Couplings Used to Align and Support 300 mm Wafer Carriers

SEMI E62 — Specification for 300 mm Front-Opening Interface Mechanical Standard (FIMS)

SEMI E84 — Specification for Enhanced Carrier Handoff Parallel I/O Interface

NOTICE: Unless otherwise indicated, all documents cited shall be the latest published versions.

5 Terminology

5.1 See SEMI E15.

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